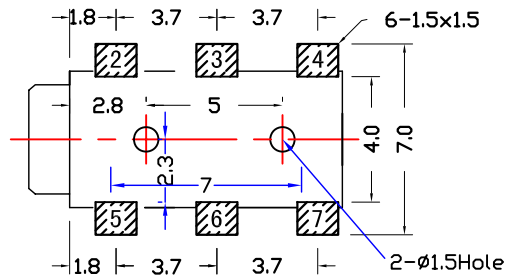
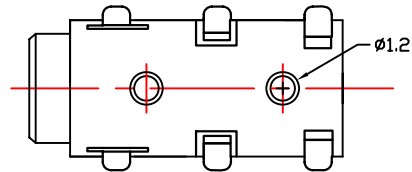
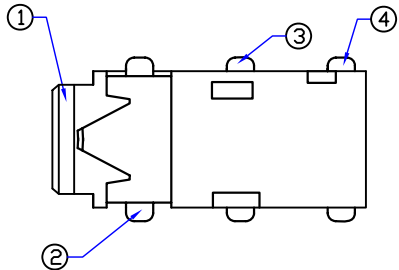
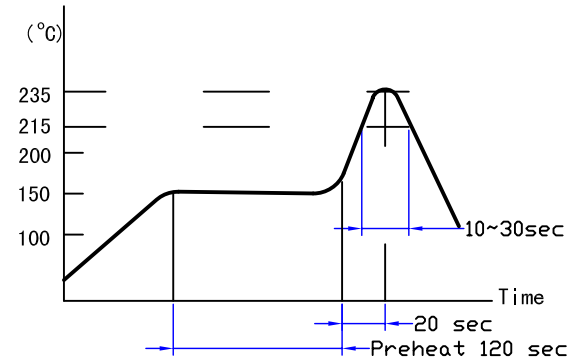


SCHEMATIC



P. C. B TERMINAL POSITION



REFLOW SOLDERING CONDITIONS

No	Parts	Material	Qty	Finish	Specifications	PJ-208-SMD	
1	Body	PA46+30%Fiber	1	94V-0	Rating: DC 12V 1A	TITLE: PHONE JACK	
2	Chip Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Contact Resistance: 30m ohm max	UNLESS OTHERWISE SPECIFIED	
3	Sleeve Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Insulation Resistance: 100M ohm at 500V DC	TOLERANCE ±0.1	
4	Ring Terminal	t:0.25 Cu-TI Alloy	1	Ep-Cu/Ni 1, Ag 1 (Silver Plating)	Dielectric Strength: AC 500V for 1 Minute	ANGLE TOL ±30°	
5					Insertion & Extraction Force:0.3-2.0kgf	UNIT: mm	SCALE:
					Life: 5.000 Cycles	DRAWN: hua	
					Taping: 1.000 Pcs/Reel	DATE: 2004-03-08	
XYFW(www.cnxyfw.com)						CHECKED:	
						DATE:	
						APPROVED:	
						DATE:	

